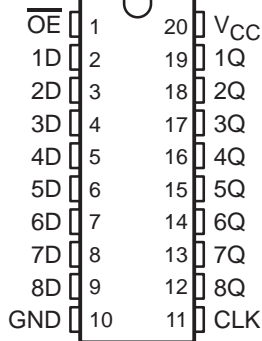


# SN54LVC574A, SN74LVC574A OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

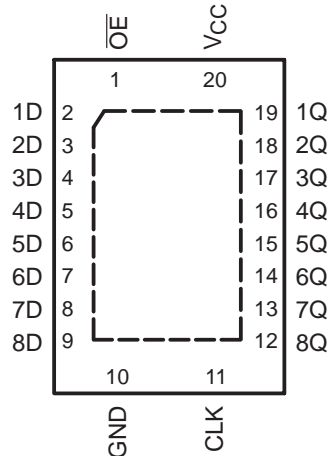
SCAS301Q – JANUARY 1993 – REVISED AUGUST 2003

- Operate From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max  $t_{pd}$  of 7 ns at 3.3 V
- Typical  $V_{OLP}$  (Output Ground Bounce) <0.8 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot) >2 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Support Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V  $V_{CC}$ )
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

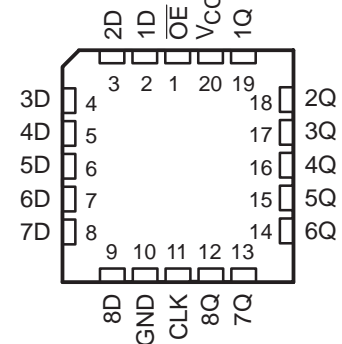
SN54LVC574A . . . J OR W PACKAGE  
SN74LVC574A . . . DB, DGV, DW, N, NS,  
OR PW PACKAGE  
(TOP VIEW)



SN74LVC574A . . . RGY PACKAGE  
(TOP VIEW)



SN54LVC574A . . . FK PACKAGE  
(TOP VIEW)



## description/ordering information

The SN54LVC574A octal edge-triggered D-type flip-flop is designed for 2.7-V to 3.6-V  $V_{CC}$  operation, and the SN74LVC574A octal edge-triggered D-type flip-flop is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

These devices feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels at the data (D) inputs.

A buffered output-enable ( $\overline{OE}$ ) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

$\overline{OE}$  does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

These devices are fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# SN54LVC574A, SN74LVC574A OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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## description/ordering information (continued)

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

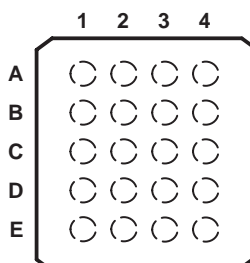
Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

### ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 20	SN74LVC574AN	SN74LVC574AN
	QFN – RGY	Reel of 1000	SN74LVC574ARGYR	LC574A
	SOIC – DW	Tube of 25	SN74LVC574ADW	LVC574A
		Reel of 2000	SN74LVC574ADWR	
	SOP – NS	Reel of 2000	SN74LVC574ANSR	LVC574A
	SSOP – DB	Reel of 2000	SN74LVC574ADBR	LC574A
	TSSOP – PW	Tube of 70	SN74LVC574APW	LC574A
		Reel of 2000	SN74LVC574APWR	
		Reel of 250	SN74LVC574APWT	
	TVSOP – DGV	Reel of 2000	SN74LVC574ADGVR	LC574A
VFBGA – GQN	Reel of 1000	SN74LVC574AGQNR	LC574A	
VFBGA – ZQN (Pb-free)		SN74LVC574AZQNR		
-55°C to 125°C	CDIP – J	Tube of 20	SNJ54LVC574AJ	SNJ54LVC574AJ
	CFP – W	Tube of 85	SNJ54LVC574AW	SNJ54LVC574AW
	LCCC – FK	Tube of 55	SNJ54LVC574AFK	SNJ54LVC574AFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

#### GQN OR ZQN PACKAGE (TOP VIEW)



#### terminal assignments

	1	2	3	4
A	1D	$\overline{OE}$	$V_{CC}$	1Q
B	3D	3Q	2D	2Q
C	5D	4D	5Q	4Q
D	7D	7Q	6D	6Q
E	GND	8D	CLK	8Q

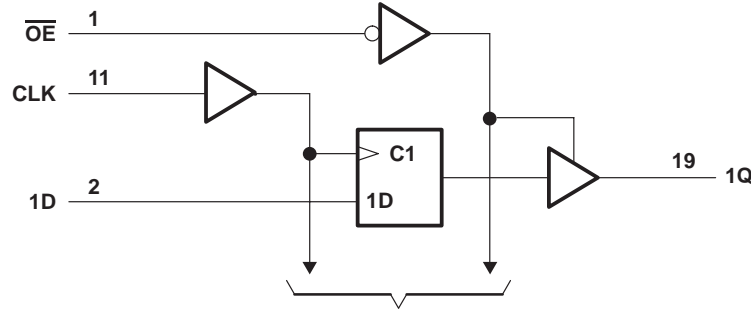
#### FUNCTION TABLE (each flip-flop)

INPUTS			OUTPUT Q
$\overline{OE}$	CLK	D	
L	↑	H	H
L	↑	L	L
L	L	X	$Q_0$
H	X	X	Z

# SN54LVC574A, SN74LVC574A OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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## logic diagram (positive logic)



To Seven Other Channels

Pin numbers shown are for the DB, DGV, DW, FK, J, N, NS, PW, RGY, and W packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	-0.5 V to 6.5 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to 6.5 V
Voltage range applied to any output in the high-impedance or power-off state, $V_O$ (see Note 1) .....	-0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, $V_O$ (see Notes 1 and 2) .....	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	-50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ ) .....	-50 mA
Continuous output current, $I_O$ .....	$\pm 50$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 100$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 3): DB package .....	70°C/W
(see Note 3): DGV package .....	92°C/W
(see Note 3): DW package .....	58°C/W
(see Note 3): GQN/ZQN package .....	78°C/W
(see Note 3): N package .....	69°C/W
(see Note 3): NS package .....	60°C/W
(see Note 3): PW package .....	83°C/W
(see Note 4): RGY package .....	37°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 2. The value of  $V_{CC}$  is provided in the recommended operating conditions table.  
 3. The package thermal impedance is calculated in accordance with JESD 51-7.  
 4. The package thermal impedance is calculated in accordance with JESD 51-5.

# SN54LVC574A, SN74LVC574A OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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## recommended operating conditions (see Note 5)

		SN54LVC574A		SN74LVC574A		UNIT
		MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage	Operating		2	3.6	V
		Data retention only		1.5		
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V			0.65 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V			1.7	
		V <sub>CC</sub> = 2.7 V to 3.6 V		2	2	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V			0.35 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V			0.7	
		V <sub>CC</sub> = 2.7 V to 3.6 V			0.8	
V <sub>I</sub>	Input voltage	0	5.5	0	5.5	V
V <sub>O</sub>	Output voltage	High or low state		0	V <sub>CC</sub>	V
		3-state		0	5.5	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 1.65 V			-4	mA
		V <sub>CC</sub> = 2.3 V			-8	
		V <sub>CC</sub> = 2.7 V			-12	
		V <sub>CC</sub> = 3 V			-24	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.65 V			4	mA
		V <sub>CC</sub> = 2.3 V			8	
		V <sub>CC</sub> = 2.7 V			12	
		V <sub>CC</sub> = 3 V			24	
Δt/Δv	Input transition rise or fall rate		6		6	ns/V
T <sub>A</sub>	Operating free-air temperature	-55	125	-40	85	°C

NOTE 5: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



# SN54LVC574A, SN74LVC574A OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	SN54LVC574A			SN74LVC574A			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V				V <sub>CC</sub> -0.2			V
		2.7 V to 3.6 V	V <sub>CC</sub> -0.2						
	I <sub>OH</sub> = -4 mA	1.65 V				1.2			
	I <sub>OH</sub> = -8 mA	2.3 V				1.7			
	I <sub>OH</sub> = -12 mA	2.7 V		2.2		2.2			
		3 V		2.4		2.4			
I <sub>OH</sub> = -24 mA	3 V		2.2		2.2				
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V						0.2	V
		2.7 V to 3.6 V			0.2				
	I <sub>OL</sub> = 4 mA	1.65 V					0.45		
	I <sub>OL</sub> = 8 mA	2.3 V					0.7		
	I <sub>OL</sub> = 12 mA	2.7 V		0.4			0.4		
	I <sub>OL</sub> = 24 mA	3 V		0.55			0.55		
I <sub>I</sub>	V <sub>I</sub> = 0 to 5.5 V	3.6 V			±5		±5	μA	
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 5.5 V	0					±10	μA	
I <sub>OZ</sub>	V <sub>O</sub> = 0 to 5.5 V	3.6 V			±15		±10	μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V	I <sub>O</sub> = 0		10		10	μA	
	3.6 V ≤ V <sub>I</sub> ≤ 5.5 V‡				10		10		
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V			500		500	μA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		4			4	pF	
C <sub>o</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	3.3 V		5.5			5.5	pF	

† All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

‡ This applies in the disabled state only.

**timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)**

		SN54LVC574A				UNIT
		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		
		MIN	MAX	MIN	MAX	
f <sub>clock</sub>	Clock frequency	150		150		MHz
t <sub>w</sub>	Pulse duration, CLK high or low	3.3		3.3		ns
t <sub>su</sub>	Setup time, data before CLK↑	2		2		ns
t <sub>h</sub>	Hold time, data after CLK↑	2		2		ns



# SN54LVC574A, SN74LVC574A OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		SN74LVC574A								UNIT
		V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>clock</sub>	Clock frequency	55		95		150		150		MHz
t <sub>w</sub>	Pulse duration, CLK high or low	9		4		3.3		3.3		ns
t <sub>su</sub>	Setup time, data before CLK↑	6		4		2		2		ns
t <sub>h</sub>	Hold time, data after CLK↑	4		2		1.5		1.5		ns

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVC574A				UNIT
			V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		
			MIN	MAX	MIN	MAX	
f <sub>max</sub>			150		150		MHz
t <sub>pd</sub>	CLK	Q	8		1	7	ns
t <sub>en</sub>	$\overline{OE}$	Q	9		1	7.5	ns
t <sub>dis</sub>	$\overline{OE}$	Q	7		0.5	6.4	ns

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER		FROM (INPUT)		TO (OUTPUT)		SN74LVC574A								UNIT
						V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		
						MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>						55		95		150		150		MHz
t <sub>pd</sub>		CLK		Q		1	21.6	1	10.5	1	8	2.2	7	ns
t <sub>en</sub>		$\overline{OE}$		Q		1	19.5	1	10.5	1	8.5	1.5	7.5	ns
t <sub>dis</sub>		$\overline{OE}$		Q		1	18.8	1	7.8	1	7	1.7	6.4	ns
t <sub>sk(o)</sub>												1		ns

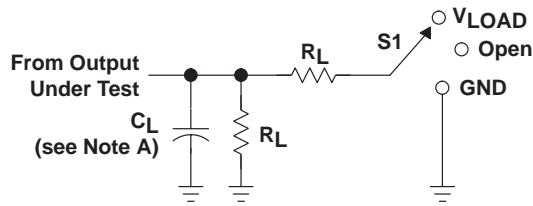
operating characteristics, T<sub>A</sub> = 25°C

PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	UNIT
			TYP	TYP	TYP	
C <sub>pd</sub>	Power dissipation capacitance per flip-flop	Outputs enabled	67	60	43	pF
	Outputs disabled	f = 10 MHz	9	9	15	

# SN54LVC574A, SN74LVC574A OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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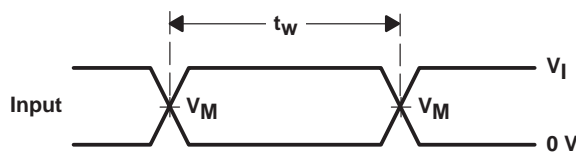
## PARAMETER MEASUREMENT INFORMATION



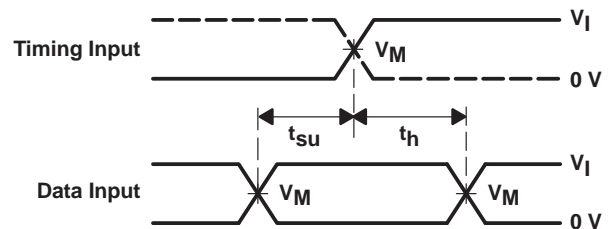
LOAD CIRCUIT

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

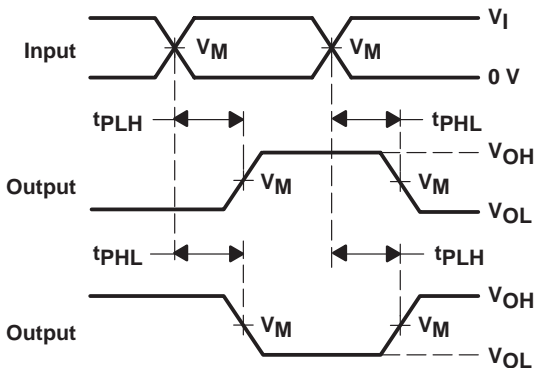
$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



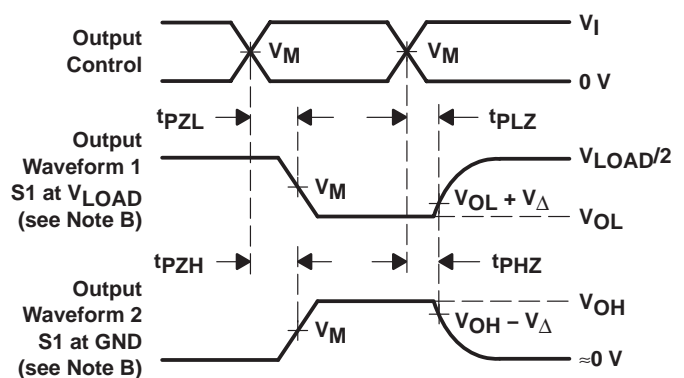
VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ .
  - The outputs are measured one at a time with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

# J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

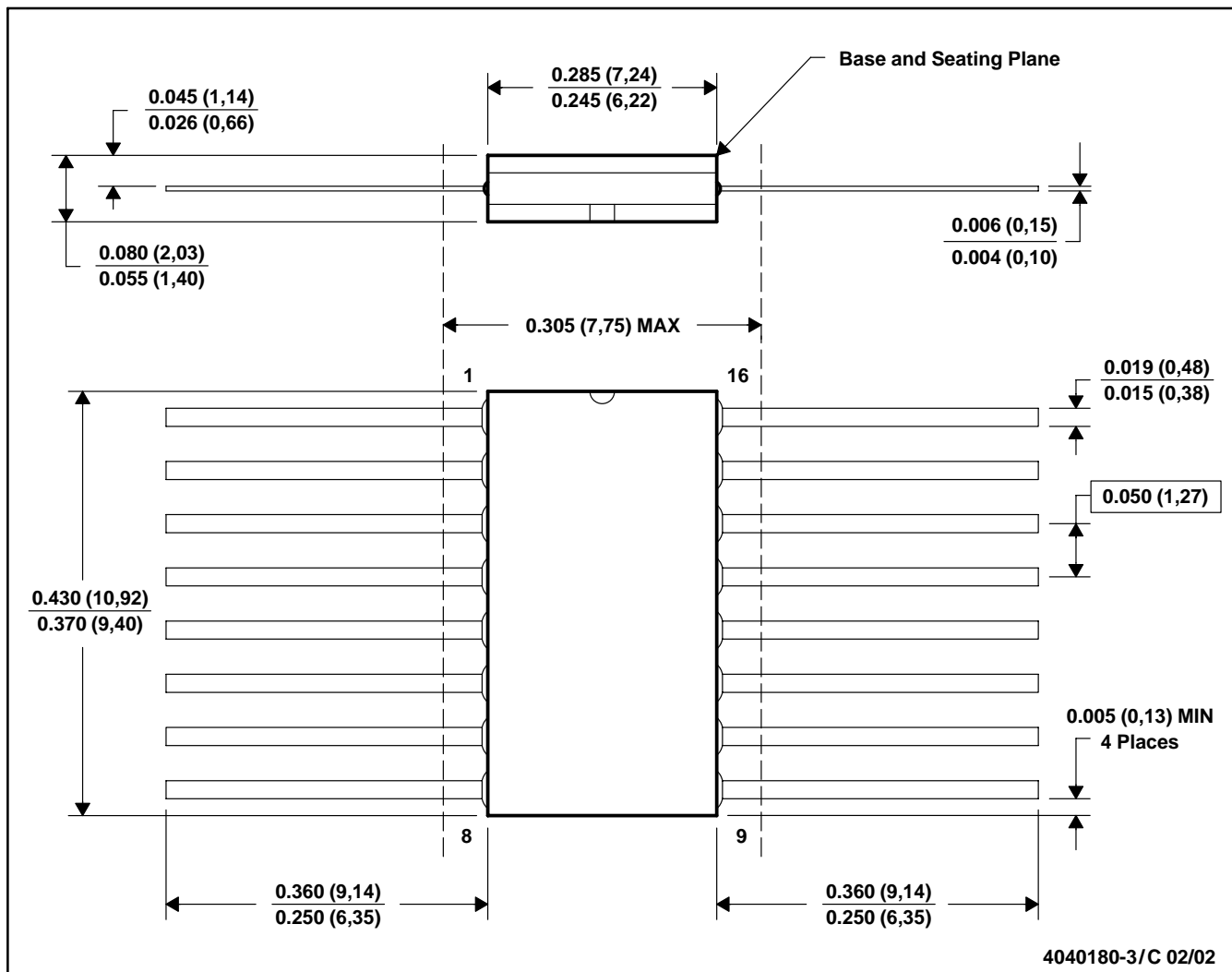


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification only.  
 E. Falls within MIL STD 1835 GDFP-1F16 and JEDEC MO-092AC

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

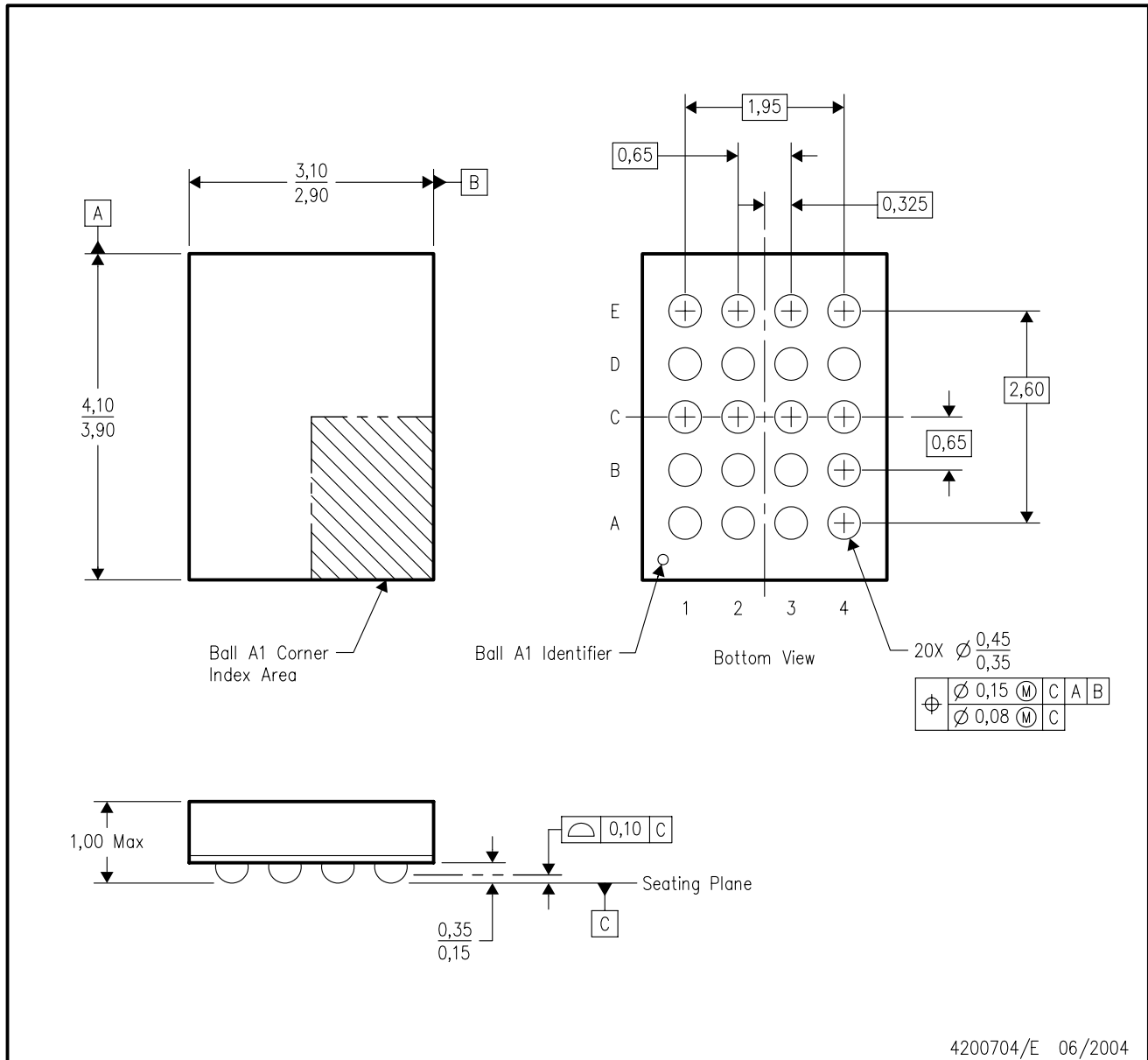
28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

GQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY

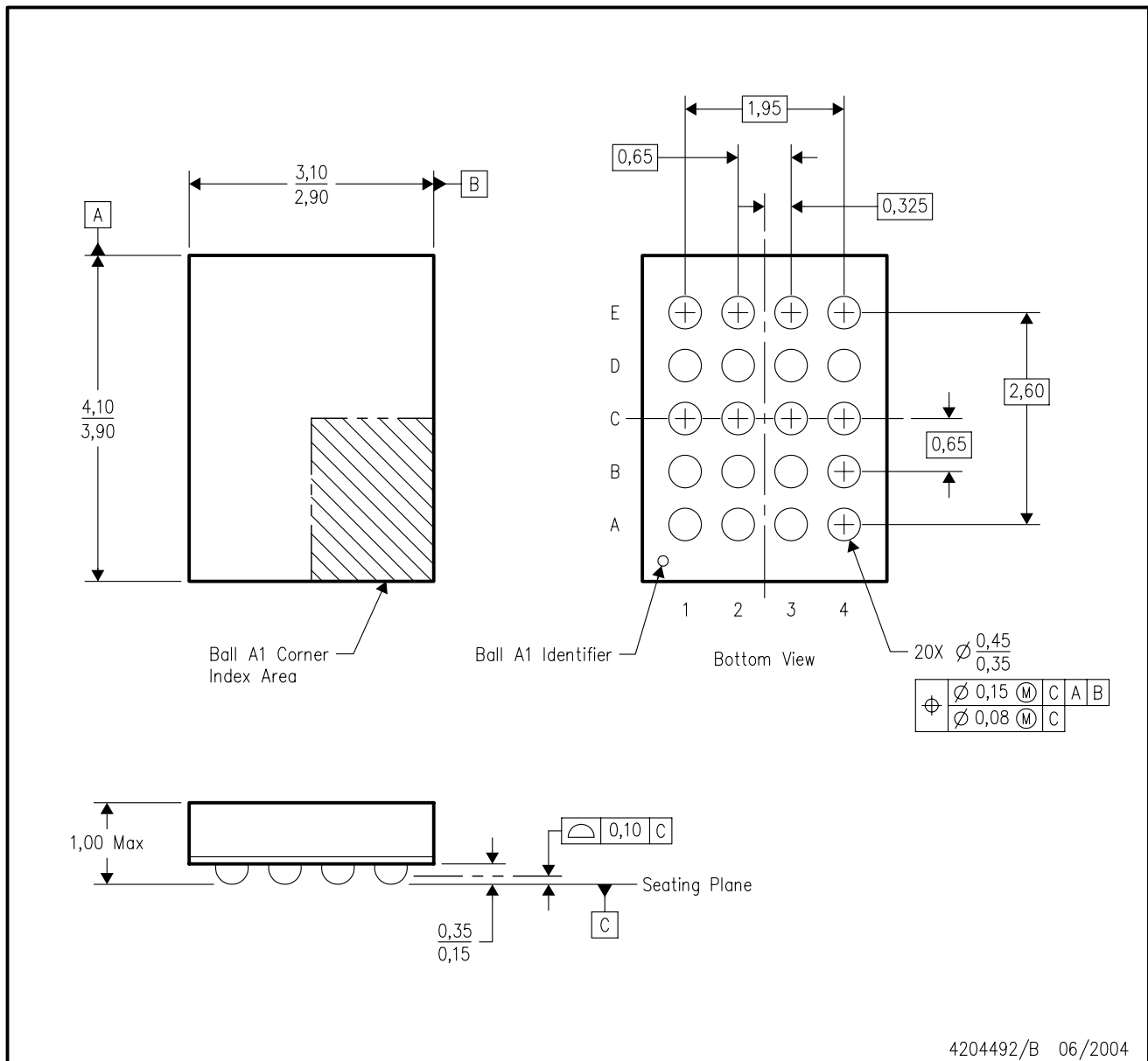


4200704/E 06/2004

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-225 variation BC.
  - D. This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.

ZQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-225 variation BC.
  - D. This package is lead-free. Refer to the 20 GQN package (drawing 4200704) for tin-lead (SnPb).

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - $\triangle D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.

DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

DW (R-PDSO-G20)

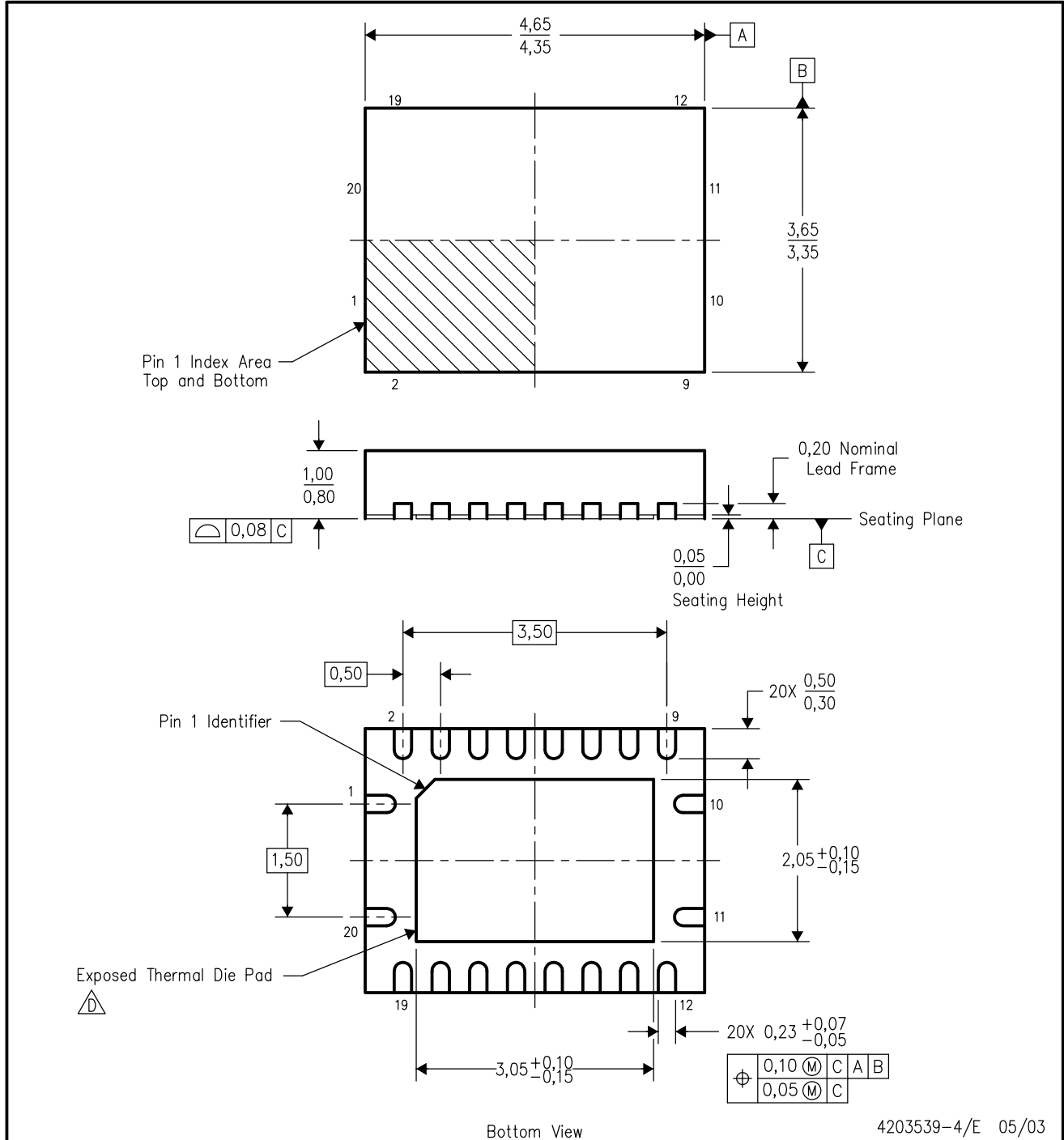
PLASTIC SMALL-OUTLINE PACKAGE




- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AC.

RGY (R-PQFP-N20)

PLASTIC QUAD FLATPACK



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. QFN (Quad Flatpack No-Lead) package configuration.
  -  The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
  - E. Package complies to JEDEC MO-241 variation BC.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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